

Description

Solderking FT-08w is a low solids water based liquid flux for effective fluxing operations. Solderking FT-08w can be used as an alternative to the traditional rosin based fluxes ,which leave a sticky residue. FT-08w is efficient on plain copper and brass. It can also be used on tinned surfaces, solder plating, nickel plating, tin/ nickel plating, silver plating and gold plating. FT-08w can be used where maximum wetting and minimum heating time is required and is suitable for dip tinning copper wires.

Specification

Typical Properties of FT-08w Soldering Flux

Colour	Pale
Specific Gravity @20°C	1.008
Ph	<2
Solids Content	4%
Flashpoint	None
Application	Dipping
Shelf Life	24 months

Storage

Shelf Life Un-opened containers- 24 months in un-opened containers below 40°C.

Shelf life Open Containers- Will depend on the environmental conditions, ensure lids are replaced and tightened to avoid evaporation.

Conditions-Store in a cool, dry area. Care should be taken to avoid temperatures below 0°C as freezing may cause separation of the flux additives.

Benefits

- Water Based
- Powerful Wetting
- Reduced Heating Time
- Non Corrosive Residues
- Mild Formulation
- Efficient on Plain Copper and Brass

Availability

Solderking manufacture all solder fluxes in the UK. Custom packaging and modifications are available on request.

FT-08w is available in the following packaging:

Flux	Packaging
FT-08w Soldering Flux	0.5 Litre
	1 Litre
	5 Litre
	10 Litre
	20 Litre

The information supplied in this technical data sheet is designed only as guidance for use and handling of the product. This information is correct to the best of our knowledge and belief at the date of publication however no guarantee is made to its accuracy. This information is related only to the specific material designated and may not be valid for such material used in combination with any other materials or in any other process.